505000386 07/12/2018

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT5047134

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SCOTT D. BRANDENBURG	07/03/2018
MANUEL R. FAIRCHILD	07/10/2018
PAUL R. MARTINDALE	07/03/2018

RECEIVING PARTY DATA

Name:	DELPHI TECHNOLOGIES, LLC
Street Address:	P. O. BOX 5052, M/C: 483-400-402
City:	TROY
State/Country:	MICHIGAN
Postal Code:	48007-5052

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16026261

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 248-813-1203

Email: kandace.k.powell@aptiv.com
Correspondent Name: DELPHI TECHNOLOGIES LLC

 Address Line 1:
 P.O. BOX 5052

 Address Line 2:
 M/C 483-400-402

Address Line 4: TROY, MICHIGAN 48007-5052

ATTORNEY DOCKET NUMBER:	P100206 US
NAME OF SUBMITTER:	LAWRENCE D. HAZELTON
SIGNATURE:	/Lawrence D. Hazelton/
DATE SIGNED:	07/12/2018

Total Attachments: 2

source=P100206_US_Assignment_signed#page1.tif source=P100206_US_Assignment_signed#page2.tif

PATENT REEL: 046330 FRAME: 0572

ASSIGNMENT

Pursuant to an agreement with my employer, I formally assign to DELPHI TECHNOLOGIES, LLC, the entire right, title and interest, in all countries, in the improvements set forth in the United States patent application P100206 entitled

ELECTRICAL-CIRCUIT ASSEMBLY WITH HEAT-SINK

for which I executed a declaration dated as indicated below. If the patent application has been filed, I authorize the Vice President of Delphi Technologies, LLC, or his designate, to insert the application number and filing date of said application here in parentheses (16/026,261 filed July 3, 2018) when known.

1

Inventor's signature	he Brah	DATE: 7/3/2018
FULL NAME:	Scott D. Brandenburg	Declaration dated:
Residence:	Kokomo, IN 46902	<u> </u>
Inventor's signature		DATE: 7/3/2018
FULL NAME:	Manuel R. Fairchild	Declaration dated:
Residence:	Kokomo, IN 46902	
Inventor's signature	Valyatishe	DATE: <u>63 JU 20</u> 18
FULL NAME:	Paul R. Martindale	Declaration dated:
Residence:	Carmal IN 16022	

PATENT REEL: 046330 FRAME: 0573

ASSIGNMENT

Pursuant to an agreement with my employer, I formally assign to DELPHI TECHNOLOGIES, LLC, the entire right, title and interest, in all countries, in the improvements set forth in the United States patent application P100206 entitled

ELECTRICAL-CIRCUIT ASSEMBLY WITH HEAT-SINK

for which I executed a declaration dated as indicated below. If the patent application has been filed, I authorize the Vice President of Delphi Technologies, LLC, or his designate, to insert the application number and filing date of said application here in parentheses (16/026,261 filed July 3, 2018) when known.

Inventor's signature		DATE:
FULL NAME:	Scott D. Brandenburg	Declaration dated:
Residence:	Kokomo, IN 46902	
Inventor's signature	MRFEIL	DATE: 7-/0-/8
FULL NAME:	Manuel R. Fairchild	Declaration dated:
Residence:	Kokomo, IN 46902	
Inventor's signature		DATE:
FULL NAME:	Paul R. Martindale	Declaration dated:
Residence:	Carmel, IN 46032	

PATENT REEL: 046330 FRAME: 0574

RECORDED: 07/12/2018